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(54) Title: RELAXATION OF STRAINED LAYERS

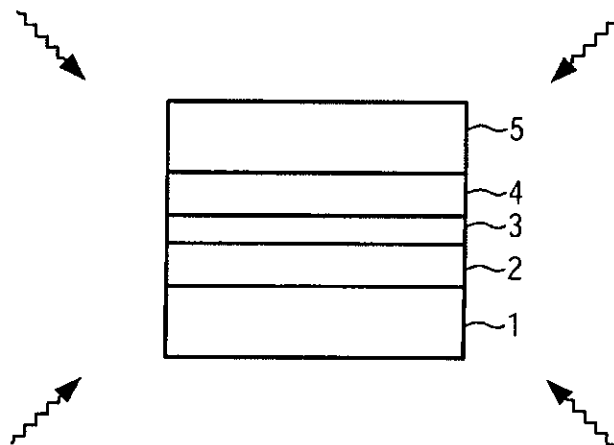


FIG. 1

(57) Abstract: The present invention relates to a method for relaxing a strained material layer, comprising depositing a first low-viscosity layer comprising a first compliant material on the strained material layer, depositing a second low-viscosity layer comprising a second compliant material on the strained material layer to form a first sandwiched structure and subjecting the first sandwiched structure to a heat treatment such that reflow of the first and the second low-viscosity layers is caused thereby at least partly relaxing the strained material layer.

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